

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	136	silicon adj (nitride or oxide)same (solder or bump) near5 (die or chip)	USPAT; EPO; JPO; DERWENT	OR	OFF	2004/12/07 13:48
L2	136	silicon adj (nitride or oxide) same (solder or bump) near5 (die or chip)	USPAT; EPO; JPO; DERWENT	OR	OFF	2004/12/07 13:48
L3	97	2 and packag\$4	USPAT; EPO; JPO; DERWENT	OR	OFF	2004/12/07 13:49

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1071	semiconductor near5 wafer and dic\$3 and die\$1 and sealant or encapsulat\$3 and transparent adj substrate	USPAT; EPO; JPO; DERWENT	OR	OFF	2004/12/07 10:20
L2	13	semiconductor near5 wafer and dic\$3 and die\$1 and (sealant or encapsulat\$3) and transparent adj substrate	USPAT; EPO; JPO; DERWENT	OR	OFF	2004/12/07 10:20